Introduction to CMOS VLSI Design

MIPS in Verilog Lecture 1

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Using slides by Jay Brockman Notre Dame 2008,
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http://www.cmosvlsi.com/coursematerials.html

MIPS Architecture

- Example: subset of MIPS processor architecture
  - Drawn from Patterson & Hennessy
- MIPS is a 32-bit architecture with 32 registers
  - Consider 8-bit subset using 8-bit datapath
  - Only implement 8 registers ($0 - $7)
  - $0 hardwired to 00000000
  - 8-bit program counter
- David Harris has developed labs to implement
  - Uses Electric CAD tools
  - Illustrate the key concepts in VLSI design

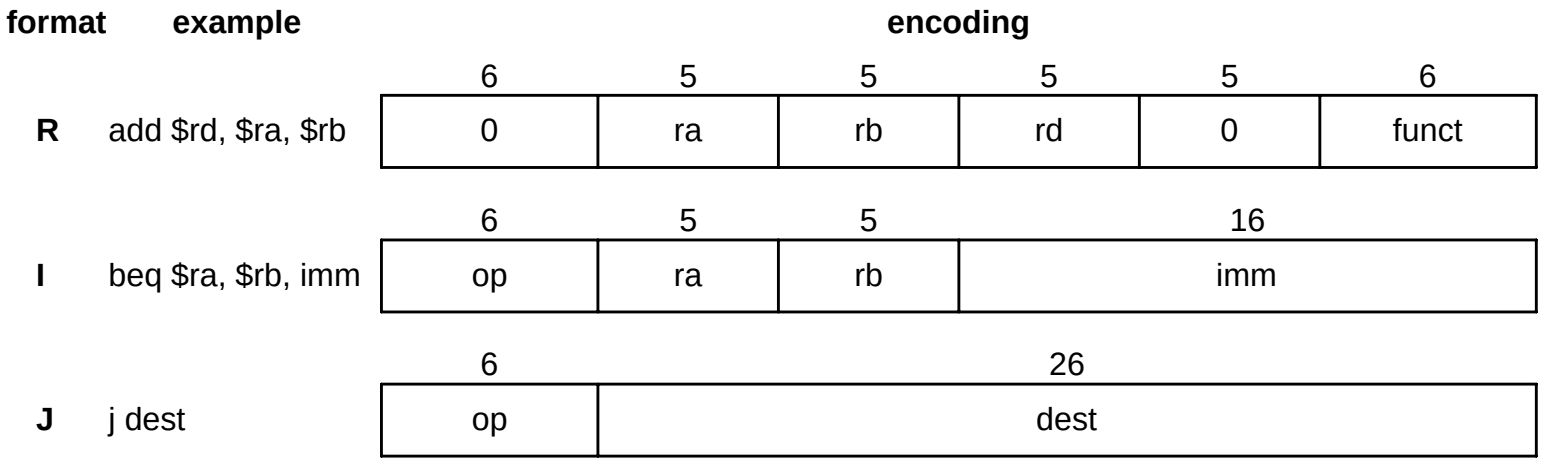
Instruction Set

Table 1.7 MIPS instruction set (subset supported)

Instruction	Function		Encoding	op	funct
`add $1, $2, $3`	addition:	$1 → $2 + $3	R	000000	100000
`sub $1, $2, $3`	subtraction:	$1 → $2 – $3	R	000000	100010
`and $1, $2, $3`	bitwise and:	$1 → $2 and $3	R	000000	100100
`or $1, $2, $3`	bitwise or:	$1 → $2 or $3	R	000000	100101
`slt $1, $2, $3`	set less than:	$1 → 1 if $2 < $3 $1 → 0 otherwise	R	000000	101010
`addi $1, $2,`	add immediate:	$1→ $2 + imm	I	001000	n/a
`beq $1, $2, imm`	branch if equal:	PC → PC + imm[a]	I	000100	n/a
`j destination`	jump:	PC_destination[a]	J	000010	n/a
`lb $1, imm($2)`	load byte:	$1 → mem[$2 + imm]	I	100000	n/a
`sb $1, imm($2)`	store byte:	mem[$2 + imm] → $1	I	110000	n/a

Instruction Encoding

- 32-bit instruction encoding
  - Requires four cycles to fetch on 8-bit datapath



Fibonacci (C)

$f_0 = 1; f_{-1} = -1$

$f_n = f_{n-1} + f_{n-2}$

f = 1, 1, 2, 3, 5, 8, 13, …

```
int fib(void)
{
  int n = 8;             /* compute nth Fibonacci number */
  int f1 = 1, f2 = -1; /* last two Fibonacci numbers */

  while (n != 0) {       /* count down to n = 0 */
    f1 = f1 + f2;
    f2 = f1 - f2;
    n = n - 1;
  }
  return f1;
}
```

Fibonacci (Assembly)

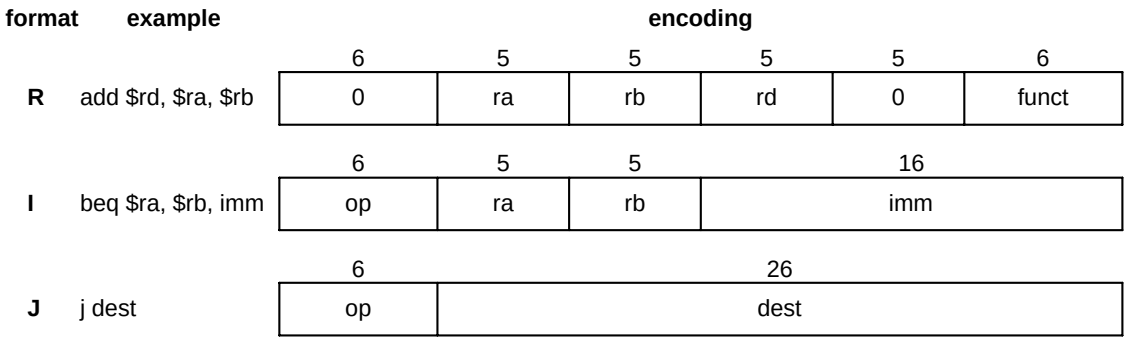
- 1st statement: n = 8
- How do we translate this to assembly?

Fibonacci (Assembly)

```
# fib.asm
# Register usage: $3: n $4: f1 $5: f2
# return value written to address 255
fib:  addi $3, $0, 8      # initialize n=8
      addi $4, $0, 1      # initialize f1 = 1
      addi $5, $0, -1     # initialize f2 = -1
loop: beq $3, $0, end     # Done with loop if n = 0
      add $4, $4, $5      # f1 = f1 + f2
      sub $5, $4, $5      # f2 = f1 - f2
      addi $3, $3, -1     # n = n - 1
      j loop              # repeat until done
end: sb $4, 255($0)       # store result in address 255
```

Fibonacci (Binary)

- 1st statement: addi $3, $0, 8
- How do we translate this to machine language?
  - Hint: use instruction encodings below



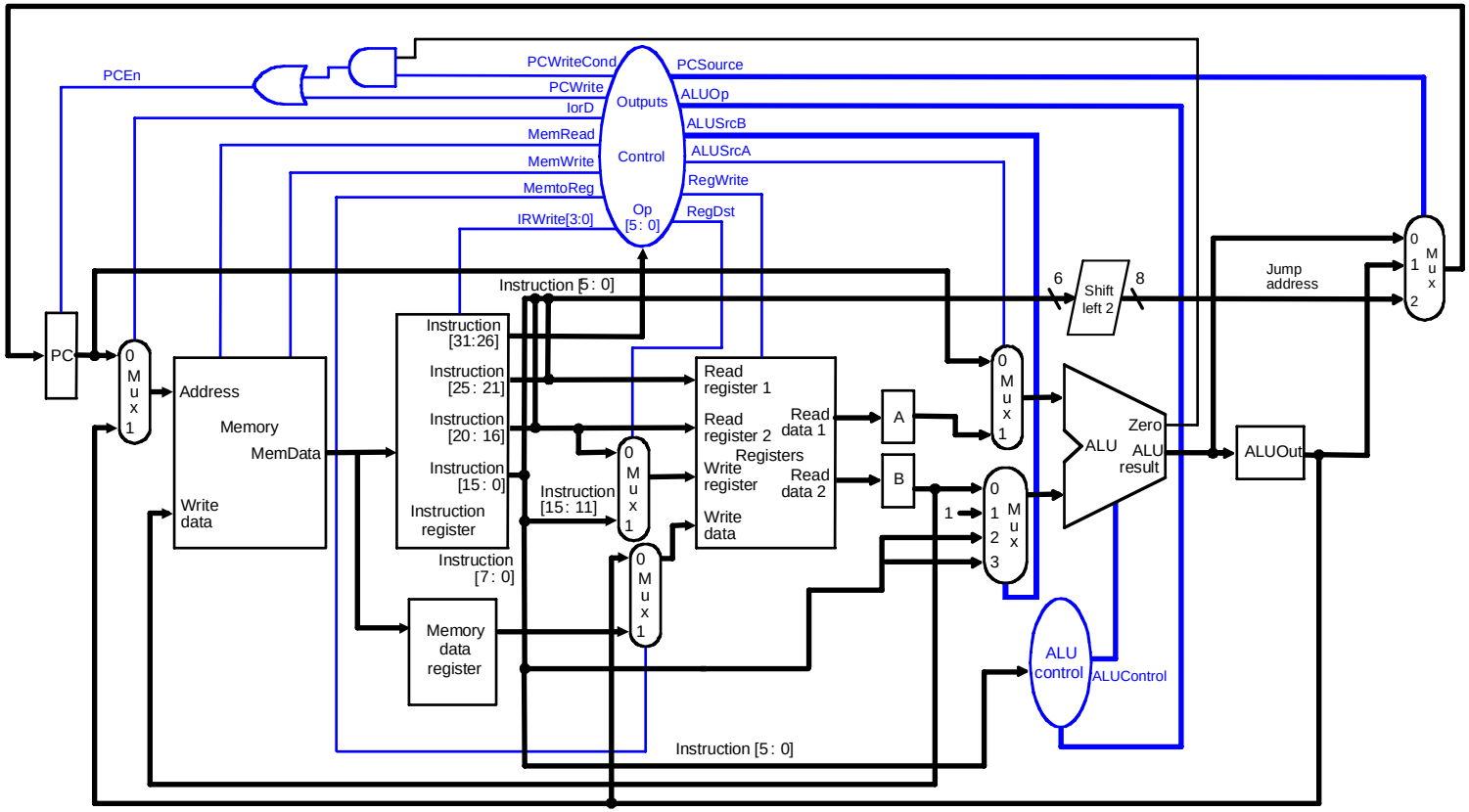
Fibonacci (Binary)

- Machine language program

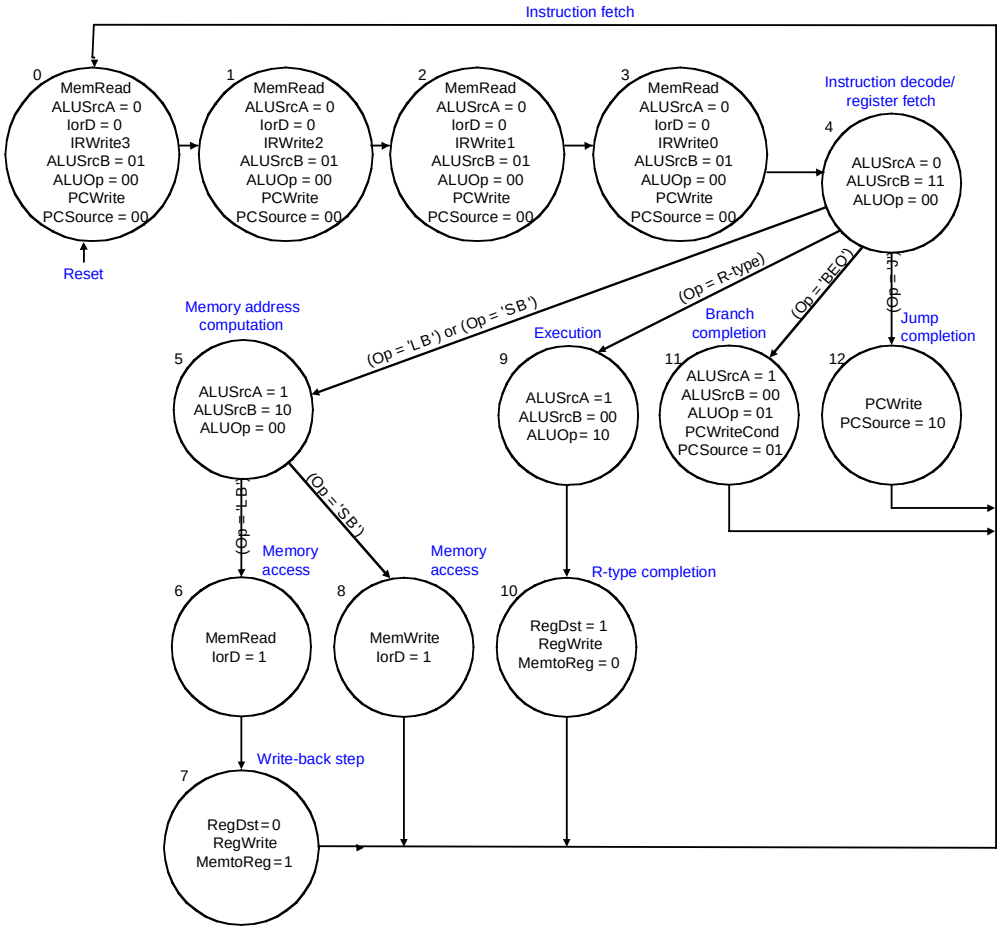
Instruction	Binary Encoding	Hexadecimal Encoding
addi $3, $0, 8	001000 00000 00011 0000000000001000	20030008
addi $4, $0, 1	001000 00000 00100 0000000000000001	20040001
addi $5, $0, -1	001000 00000 00101 1111111111111111	2005ffff
beq $3, $0, end	000100 00011 00000 0000000000000101	10600005
add $4, $4, $5	000000 00100 00101 00100 00000 100000	00852020
sub $5, $4, $5	000000 00100 00101 00101 00000 100010	00852822
addi $3, $3, -1	001000 00011 00011 1111111111111111	2063ffff
j loop	000010 00000000000000000000000011	08000003
sb $4, 255($0)	110000 00000 00100 0000000011111111	a00400ff

MIPS Microarchitecture

- Multicycle μarchitecture from Patterson & Hennessy

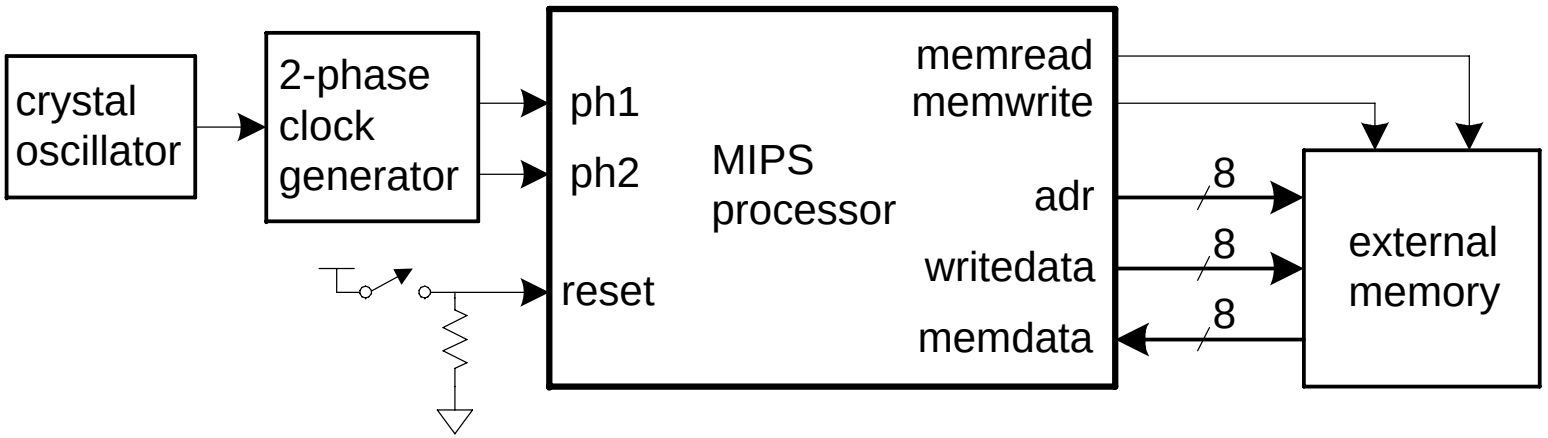


Multicycle Controller

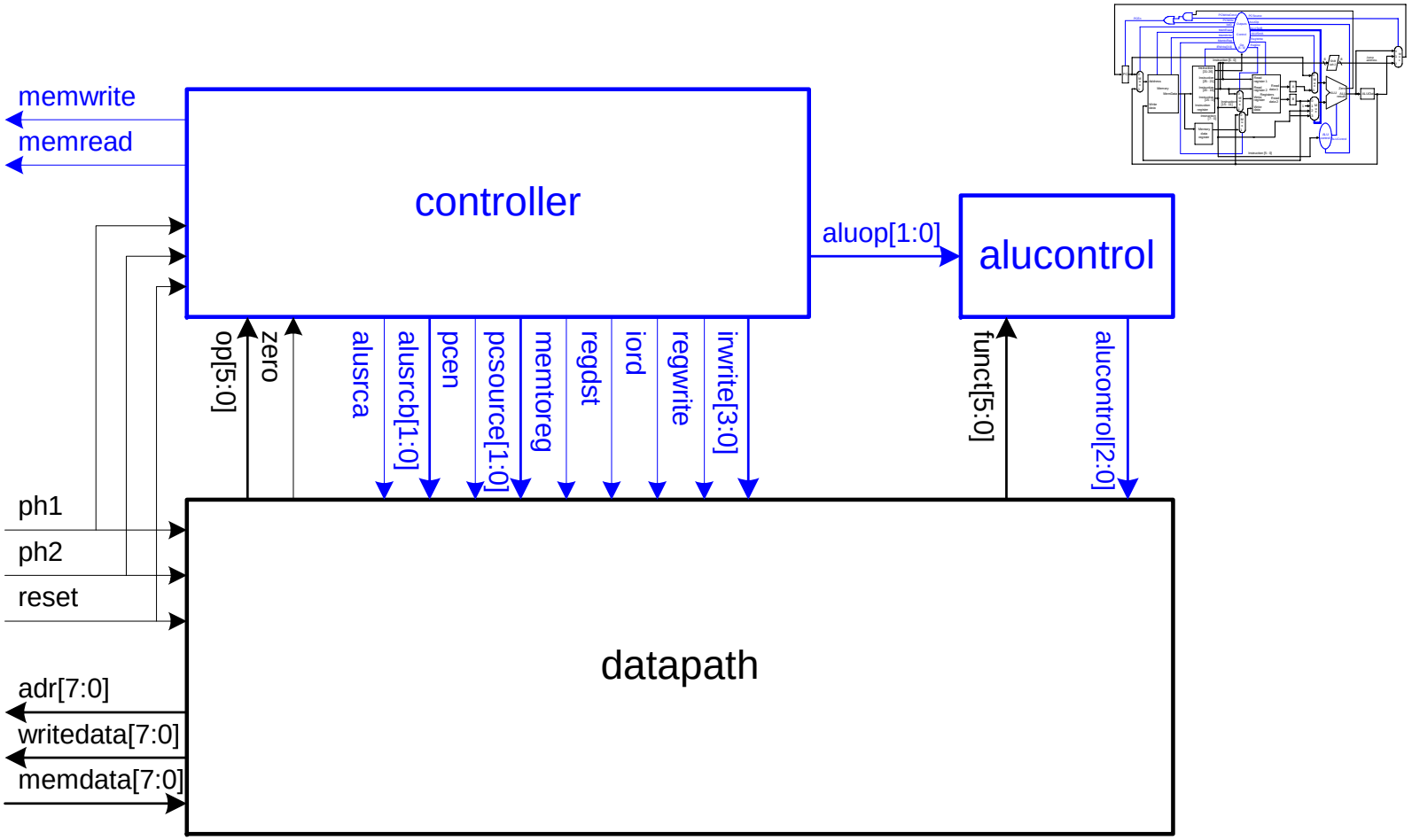


Logic Design

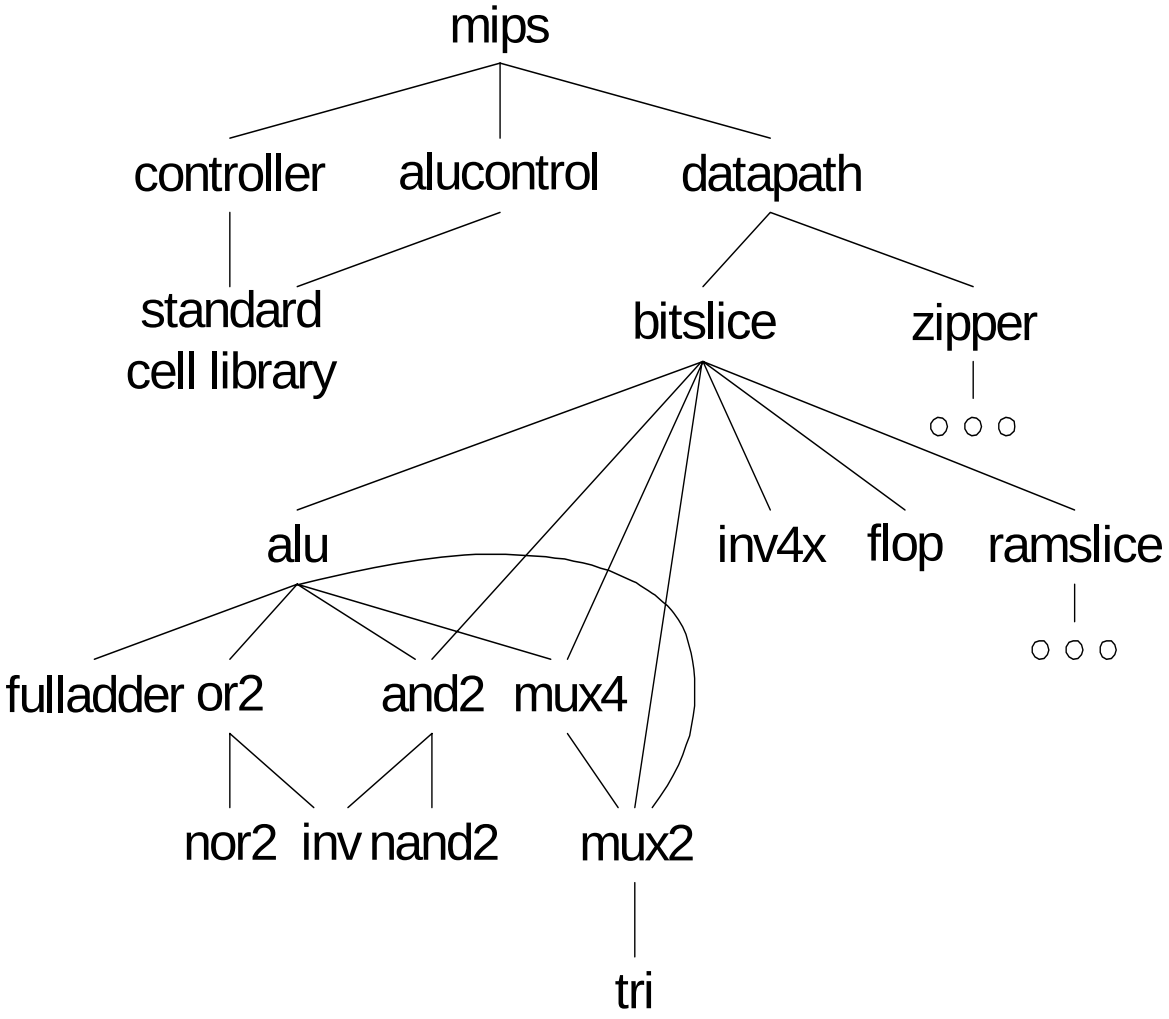
- Start at top level
  - Hierarchically decompose MIPS into units
- Top-level interface



Block Diagram



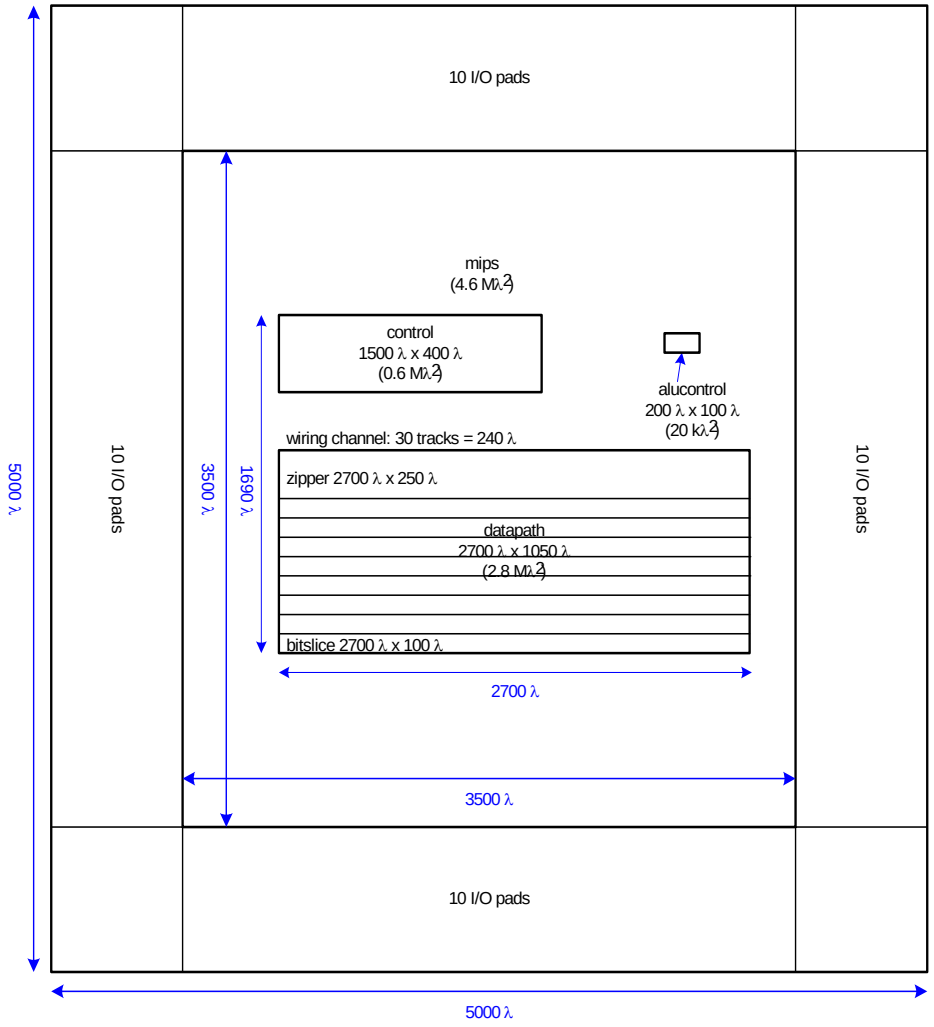
Hierarchical Design



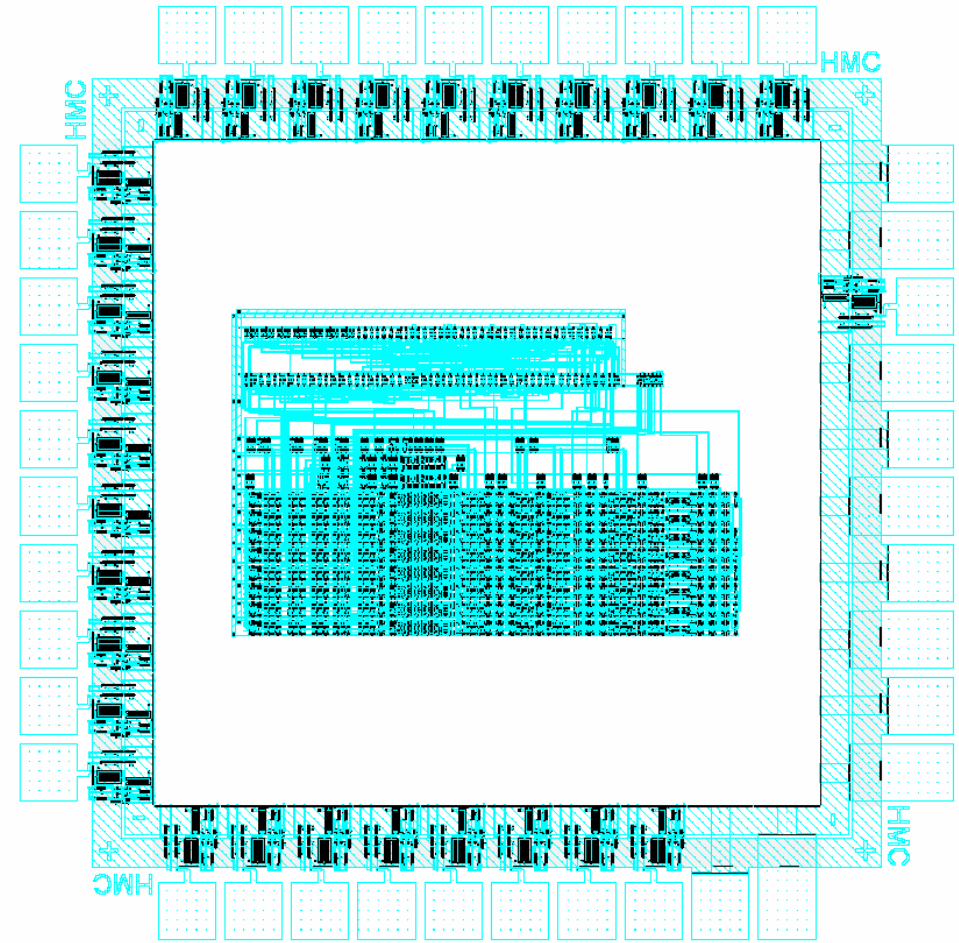
Physical Design

- Floorplan
- Standard cells
  - Place & route
- Datapaths
  - Slice planning
- Area estimation

MIPS Floorplan

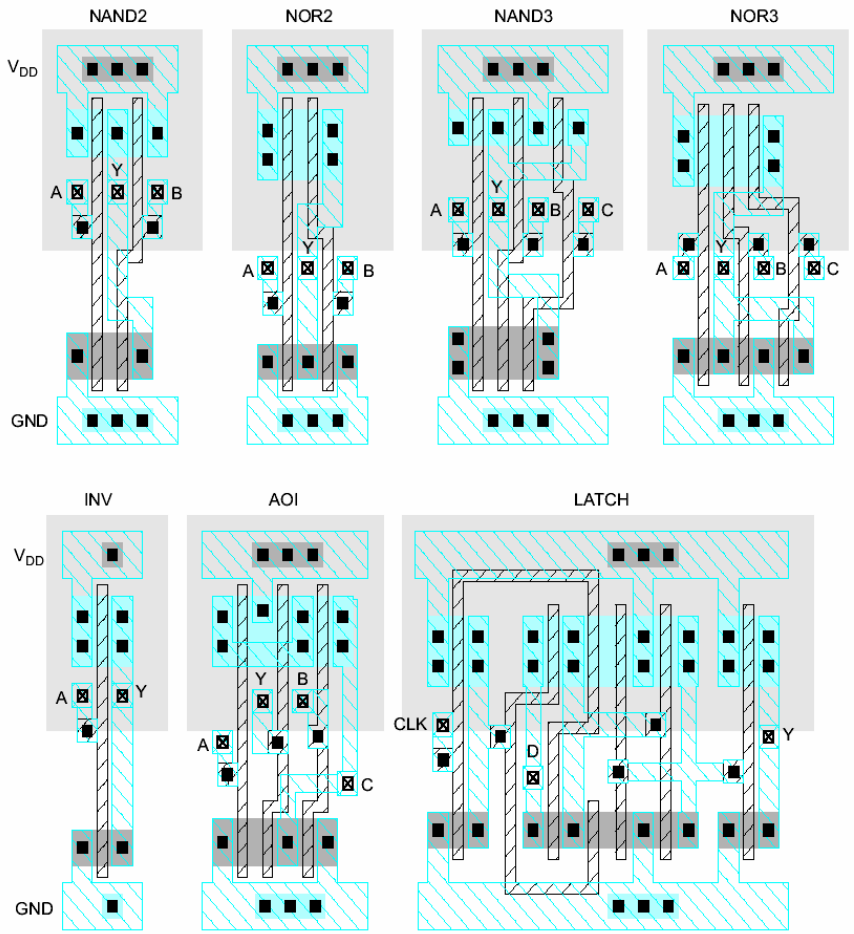


MIPS Layout



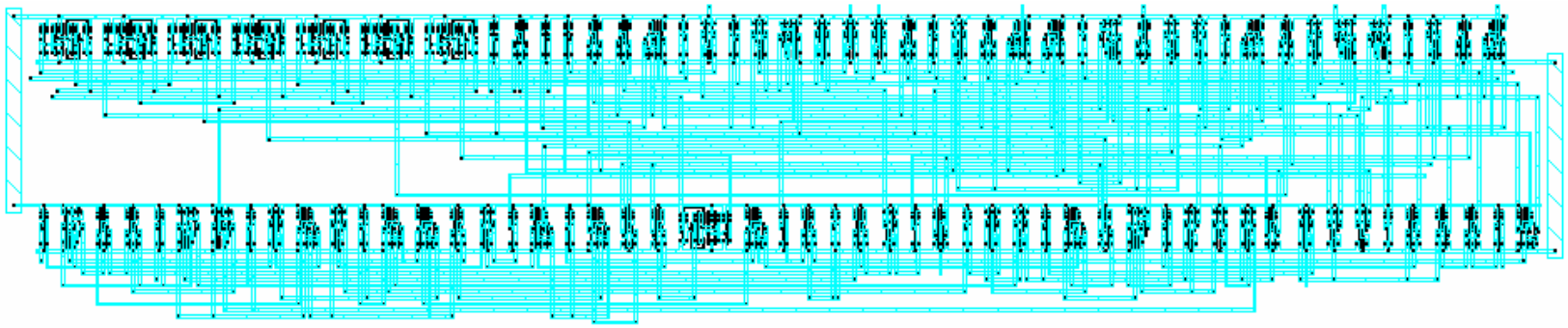
Standard Cells

- Uniform cell height
- Uniform well height
- M1 V_{DD} and GND rails
- M2 Access to I/Os
- Well / substrate taps
- Exploits regularity



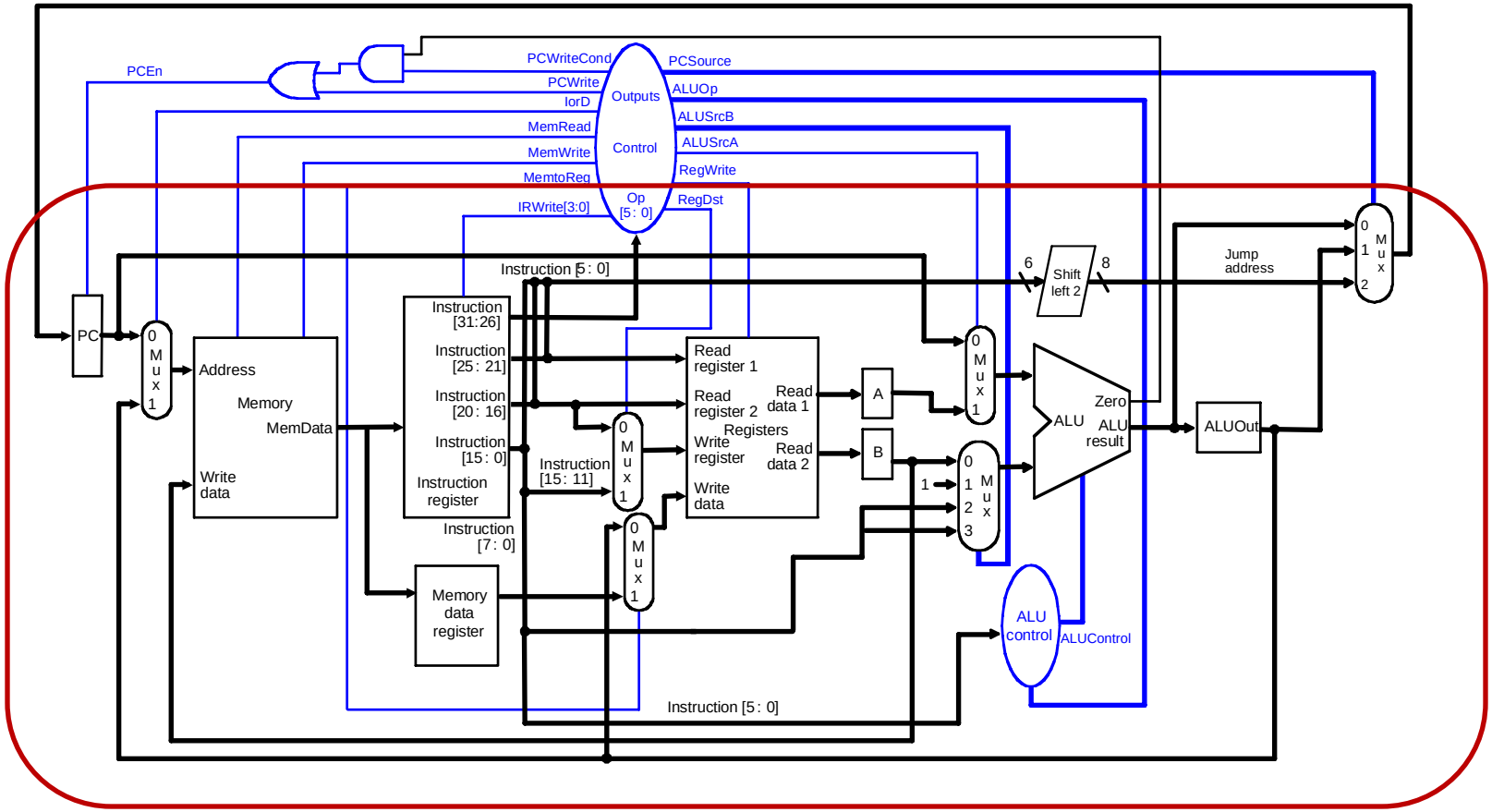
Synthesized Controller

- Synthesize HDL into gate-level netlist
- Place & Route using standard cell library



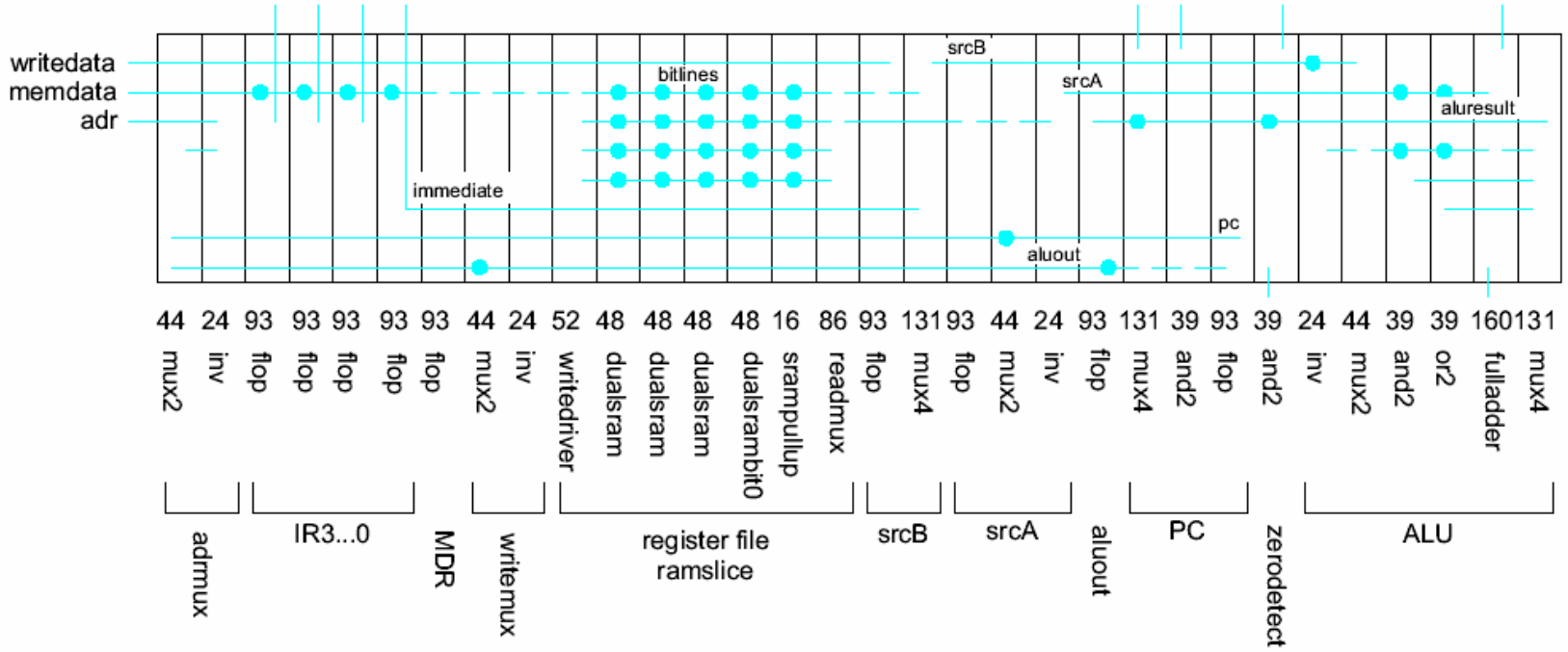
MIPS Datapath

- Multicycle μarchitecture from Patterson & Hennessy



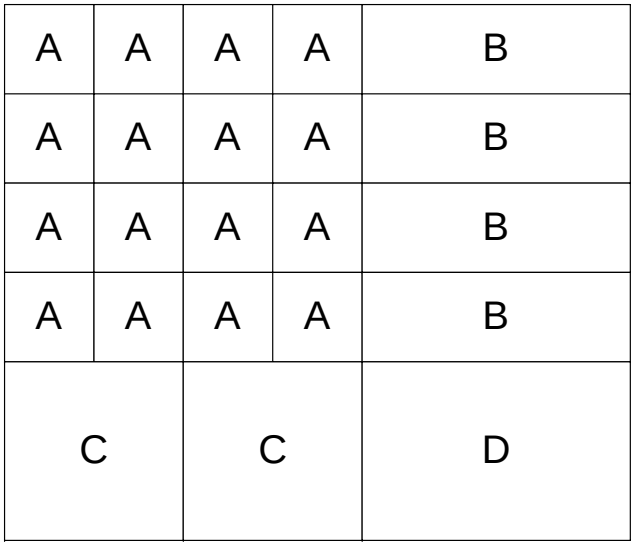
Slice Plans

- Slice plan for bitslice
  - Cell ordering, dimensions, wiring tracks
  - Arrange cells for wiring locality



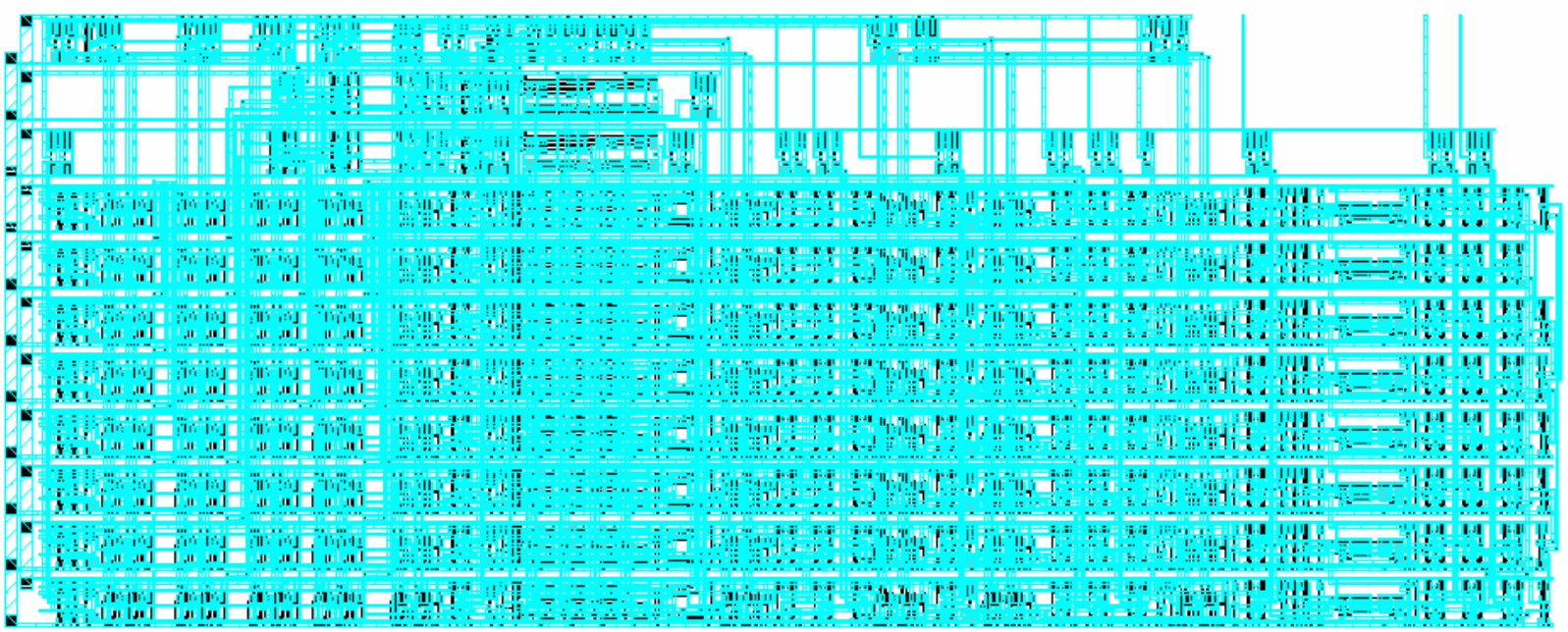
Pitch Matching

- Synthesized controller area is mostly wires
  - Design is smaller if wires run through/over cells
  - Smaller = faster, lower power as well!
- Design snap-together cells for datapaths and arrays
  - Plan wires into cells
  - Connect by abutment
    - Exploits locality
    - Takes lots of effort



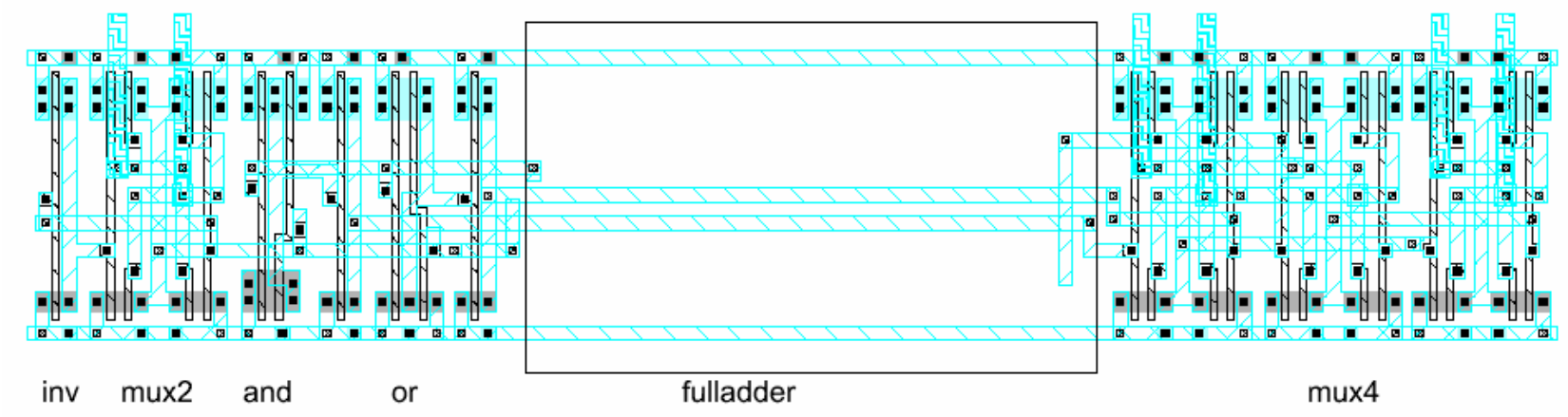
MIPS Datapath

- 8-bit datapath built from 8 bitslices (regularity)
- Zipper at top drives control signals to datapath



MIPS ALU

- Arithmetic / Logic Unit is part of bitslice



Area Estimation

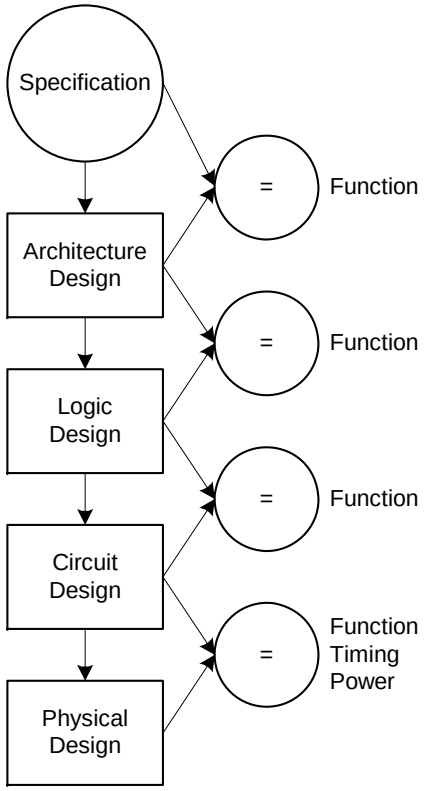
- Need area estimates to make floorplan
  - Compare to another block you already designed
  - Or estimate from transistor counts
  - Budget room for large wiring tracks
  - Your mileage may vary!

Table 1.10 Typical layout densities

Element	Area
random logic (2-level metal process)	1000 – 1500 λ^2 / transistor
datapath	250 – 750 λ^2 / transistor or 6 WL + 360 λ^2 / transistor
SRAM	1000 λ^2 / bit
DRAM (in a DRAM process)	100 λ^2 / bit
ROM	100 λ^2 / bit

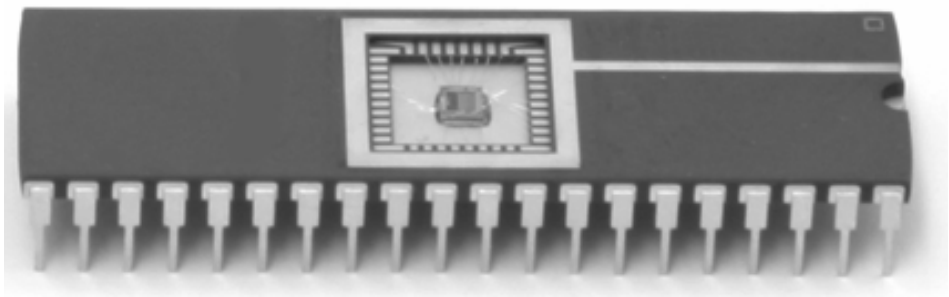
Design Verification

- Fabrication is slow & expensive
  - MOSIS 0.6μm: $1000, 3 months
  - State of art: $1M, 1 month
- Debugging chips is very hard
  - Limited visibility into operation
- Prove design is right before building!
  - Logic simulation
  - Ckt. simulation / formal verification
  - Layout vs. schematic comparison
  - Design & electrical rule checks
- Verification is > 50% of effort on most chips!



Fabrication & Packaging

- Tapeout final layout
- Fabrication
  - 6, 8, 12” wafers
  - Optimized for throughput, not latency (10 weeks!)
  - Cut into individual dice
- Packaging
  - Bond gold wires from die I/O pads to package



Testing

- Test that chip operates
  - Design errors
  - Manufacturing errors
- A single dust particle or wafer defect kills a die
  - Yields from 90% to < 10%
  - Depends on die size, maturity of process
  - Test each part before shipping to customer